

Loctite® 3533 Low viscosity fill encapsulant Fill Encapsulant

Category : Polymer , Adhesive , Thermoset

Material Notes:

COB/DCA Encapsulants are essential to the reliability of flip chip assemblies because they minimize the thermal mismatch between the flip chip and substrate. Loctite® Underfills and Encapsulants improve assembly operations by providing superior reliability and faster throughput. Improved reliability is achieved through products that have a high Tg, low CTE, high throughput and excellent adhesion. Faster throughput and higher yields are achieved through faster flow characteristics and increased cure speeds. Loctite® 3533 Low viscosity fill encapsulant Fill Encapsulant Low CTE and high Tg specifically designed to provide the highest reliability in demanding COB, MCM, BGA, and PGA encapsulating applications.

Order this product through the following link:

http://www.lookpolymers.com/polymer_Loctite-3533-Low-viscosity-fill-encapsulantFill-Encapsulant.php

Physical Properties	Metric	English	Comments
Density	1.78 g/cc	0.0643 lb/in ³	
Viscosity	50000 cP	50000 cP	Haake cone and plate rheometer @ 5/sec (35mm/2° cone)

Thermal Properties	Metric	English	Comments
CTE, linear	19.0 µm/m-°C	10.6 µin/in-°F	
	@Temperature 20.0 °C	@Temperature 68.0 °F	
Glass Transition Temp, Tg	155 °C	311 °F	

Electrical Properties	Metric	English	Comments
Volume Resistivity	4.20e+15 ohm-cm	4.20e+15 ohm-cm	
Surface Resistance	4.20e+16 ohm	4.20e+16 ohm	

Processing Properties	Metric	English	Comments
Cure Time	30.0 min	0.500 hour	Full Cure
	@Temperature 150 °C	@Temperature 302 °F	
Shelf Life	3.00 Month	3.00 Month	
	@Temperature -40.0 °C	@Temperature -40.0 °F	

Descriptive Properties	Value	Comments
Color	Black	

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